AXA Series　Low Temperature・Heat・Humidity Resistance Test Reports　Contents

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Low-Temperature Resistance test | **TEST REPORT**

Product:	SD Memory Card Socket
Data No.	AXA2R73061-M-758
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Purpose

To confirm characteristics of Low-Temperature Resistance.

Sample

SD Memory card socket (Applicable to SDIO R-type, standard type)
Stand-off 0 mm 【AXA2R73061-M】 (n=3)

Test condition

Temperature: -55°C
Time: 1000 h

Criteria

Insulation Resistance:

Min.100 MΩ at D.C.500V

Breakdown Voltage Resistance:

A.C. 500V/1min. (Detection current: 1mA)

Contact Resistance:

Signal Contact: 40mΩ maximum change

Detection Contact: Max.150 mΩ

Card Insertion Force:

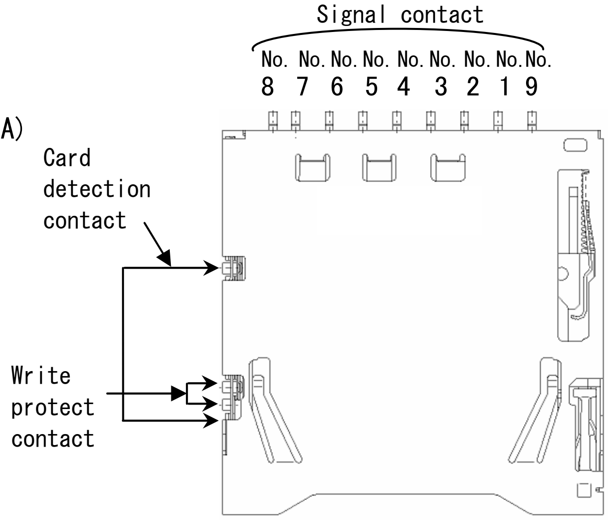
Max. 40 N

Card Removal Force:

Min. 1 N Max. 40 N

Apperance:

There is no deforming, camber and crack of molded parts.



Test result

Insulation Resistance

Measurement part	Test result
Contiguity terminals	More than 100MΩ
Between shell and each contact	

Breakdown voltage Resistance

Measurement part	Test result
Contiguity terminals	There are no short and damage at AC 500V for 1 minute
Between shell and each contact	

DATE: Aug., 29, 2014

HONDA TSUSHIN KOGYO CO., LTD.	DRAWN BY T.Sato	CHECKED BY S.Oshima
	CHECKED BY ———	APPROVED BY S.Furusawa

Low-Temperature Resistance test	TEST REPORT

Product:	SD Memory Card Socket
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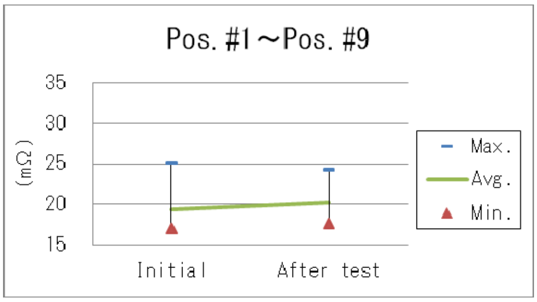
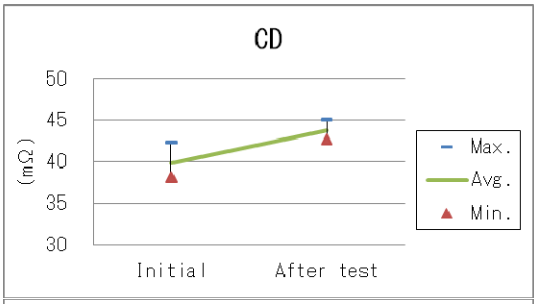
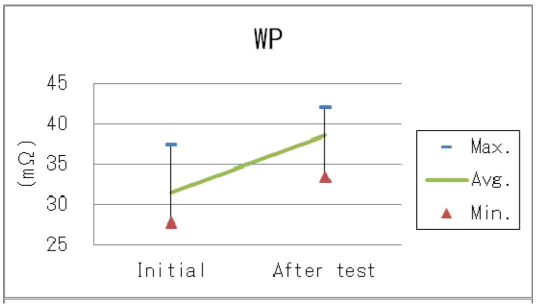
Contact Resistance



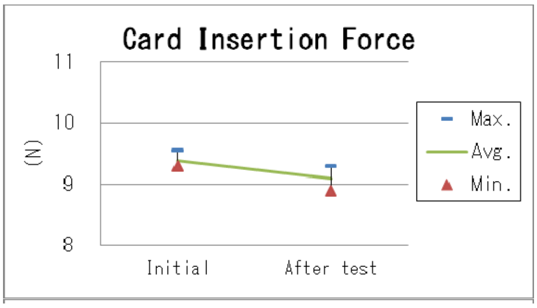
Amount of change in Contact Resistance
[mΩ]

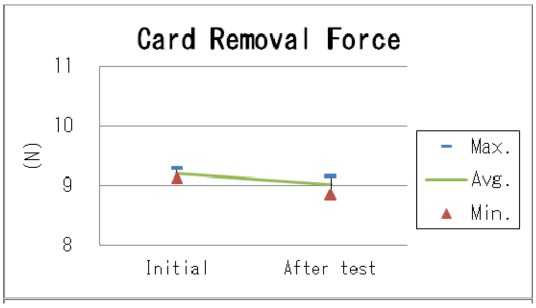
	Pos.#1～Pos.#9
	After test
Max.	3.23
Avg.	0.90
Min.	-0.86





Card Insertion and Removal Force variations





Card Insertion Force: The load for cum-lock

Card Removal Force: The load for cum-unlock

Apperance: There was no deforming, camber and crack of molded parts

Judgement

No problems are observed.

Uncontrolled

Heat Resistance Test	TEST REPORT

Product: SD Memory Card Socket
Data No.　AXA2R73061-M-768
Page No.　　　1／3

Purpose　To confirm characteristics of heat resistance in accordance with spec.

Sample　SD Memory Card Socket (Applicable to SDIO　R-type, standard type)
Stand-off 0mm　【AXA2R73061-M】　(n = 6)

Test condition
Temperature　:　90℃
Time　:　1000h

Criteria
- Insulation resistance　:　Min.100 MΩ
- Breakdown voltage resistance :　Min.AC 500V/1min　(Detection current : 1mA)
- Contact resistance　:　Signal contact　Max.100 mΩ
  :　Detection contact　Max.150 mΩ
- Card insertion force　:　Max.　40 N
- Card removal force　:　Min.　1 N　40 N
- Apperance　:　There is no deforming, camber and crack of molded parts.

Test result

・Insulation resistance

Measurement part	Test result
Contiguity terminals	More than 100 MΩ
Between shell and each contact	

・Breakdown voltage resistance

Measurement part	Test result
Contiguity terminals	There are no short and damage at AC 500V for 1 minute
Between shell and each contact	

DATE:Sep., 24, 2019

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Heat Resistance Test	TEST REPORT

Product: SD Memory Card Socket
Data No. AXA2R73061-M-768
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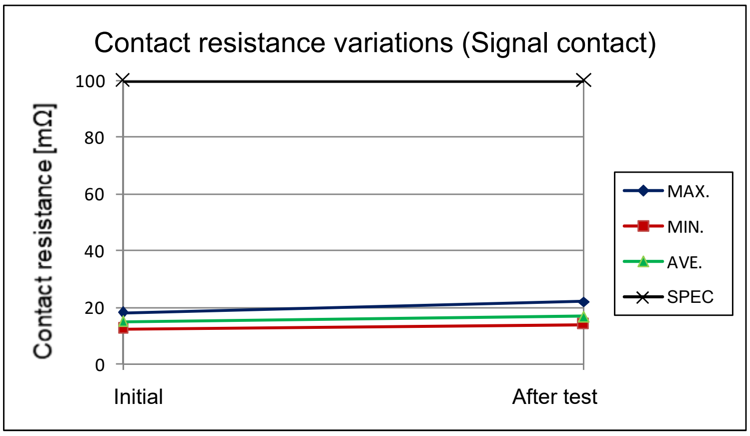
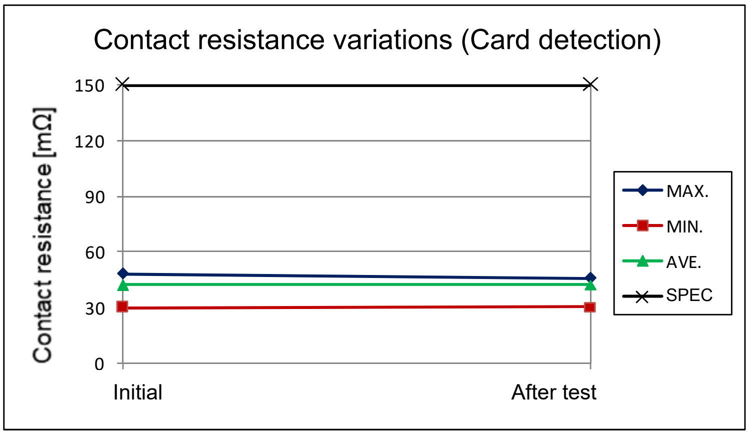
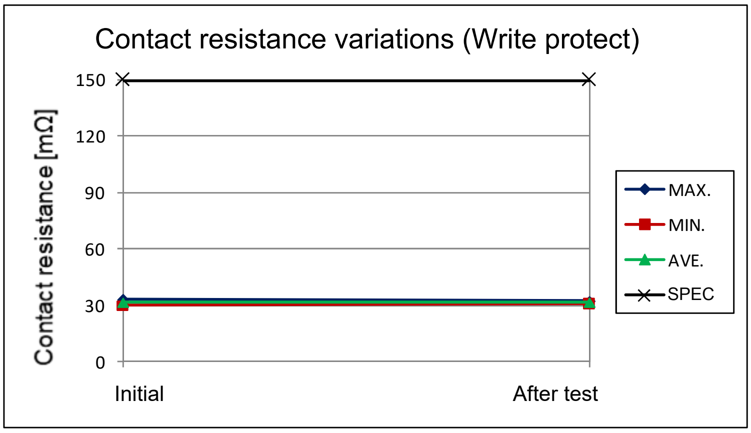
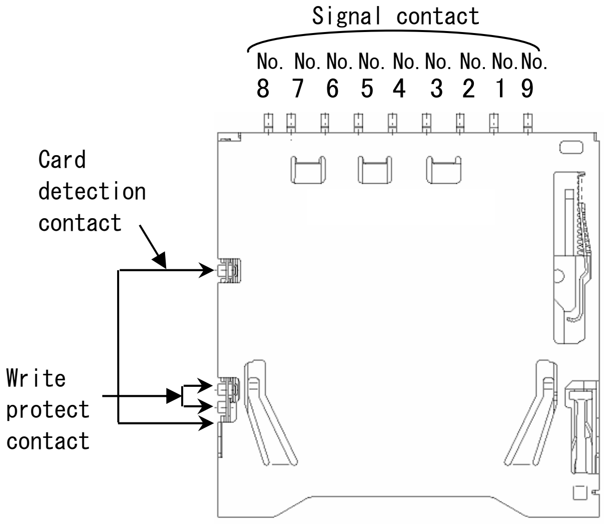
·Contact resistance

Contact resistance

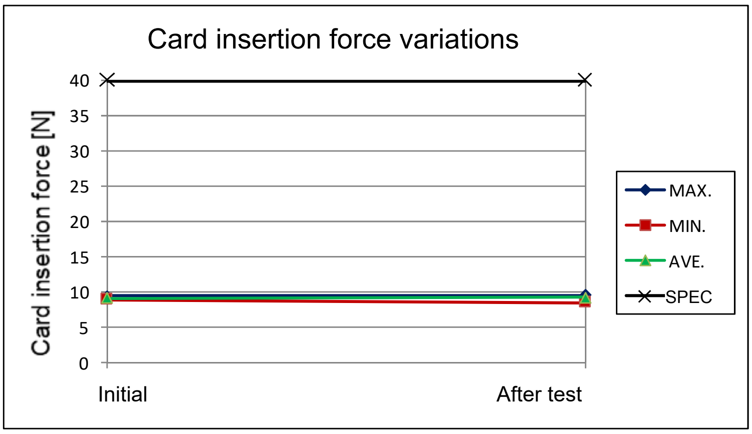


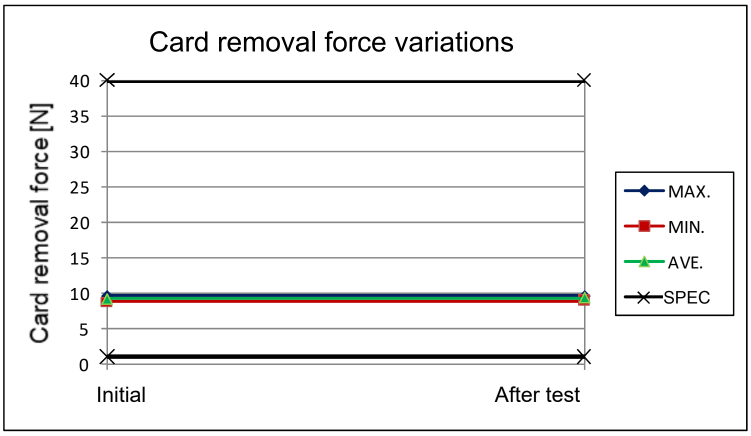






・Card insertion and removal force variations





・Card insertion force　：　The load for cum-lock
・Card removal force　：　The load for cum-unlock

・Apperance　：　There was no deforming, camber and crack of molded parts

Judgment	No problems are observed.

Humidity Resistance Test	TEST REPORT

Product: SD Memory Card Socket
Data No. AXA2R73061-M-769
Page No. 1／3

Purpose To confirm characteristics of huidity resistance in accordance with spec.

Sample SD Memory Card Socket (Applicable to SDIO R-type, standard type)
Stand-off 0mm 【AXA2R73061-M】 (n = 6)

Test condition
Temperature : 60℃
Humidity : 95 %
Time : 1000h

Criteria
- Insulation resistance : Min.100 MΩ
- Breakdown voltage resistance : Min.AC 500V/1min (Detection current : 1mA)
- Contact resistance : Signal contact Max.100 mΩ
  : Detection contact Max.150 mΩ
- Card insertion force : Max. 40 N
- Card removal force : Min. 1 N 40 N
- Apperance : There is no deforming, camber and crack of molded parts.

Test result

・Insulation resistance

Measurement part	Test result
Contiguity terminals	More than 100 MΩ
Between shell and each contact	

・Breakdown voltage resistance

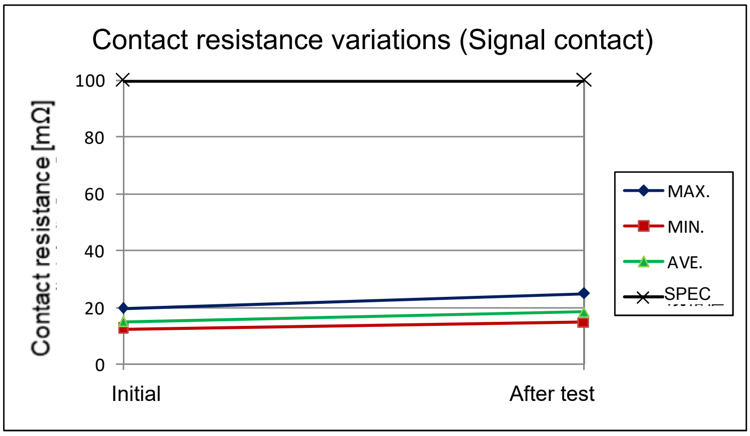
Measurement part	Test result
Contiguity terminals	There are no short and damage at AC 500V for 1 minute
Between shell and each contact	

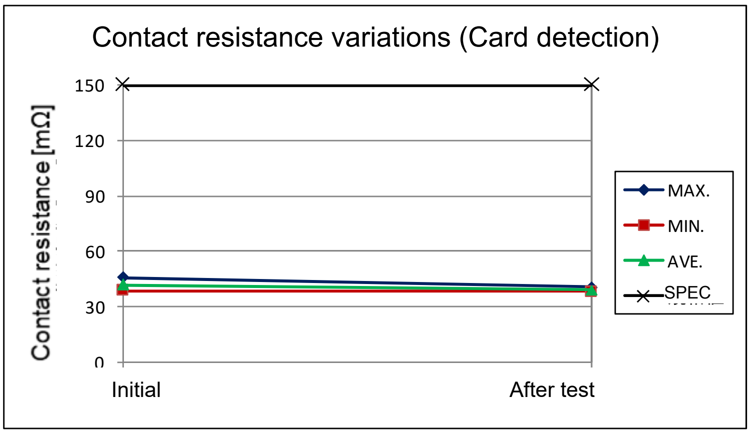
DATE:Sep., 24, 2019

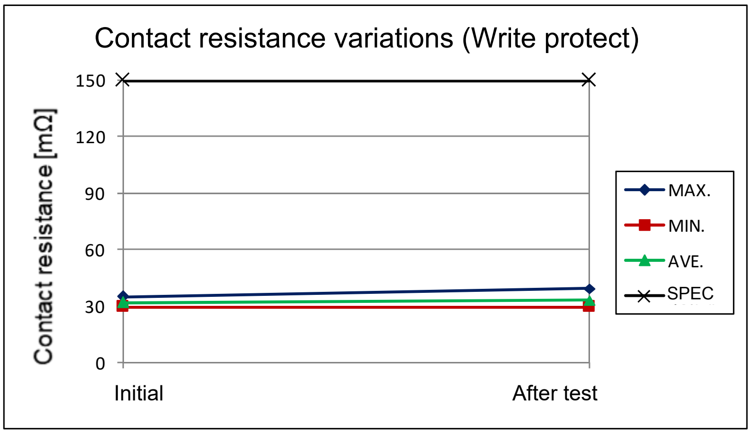
HONDA TSUSHIN KOGYO CO., LTD.	DRAWN BY T.Sato	CHECKED BY S.Yoshida
	CHECKED BY ――――	APPROVED BY Y.Kato

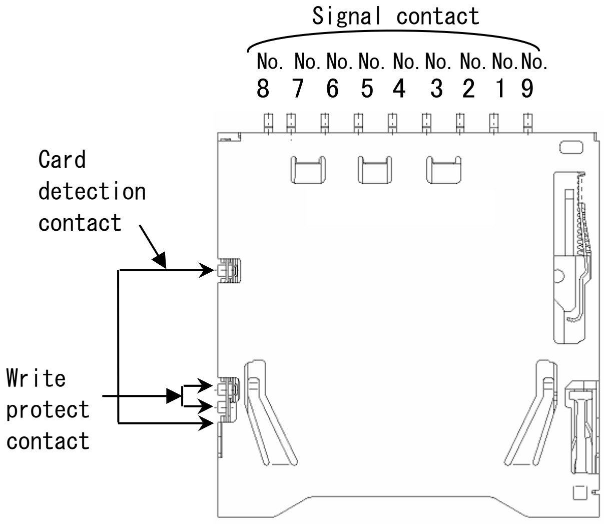
・Contact resistance

Contact resistance

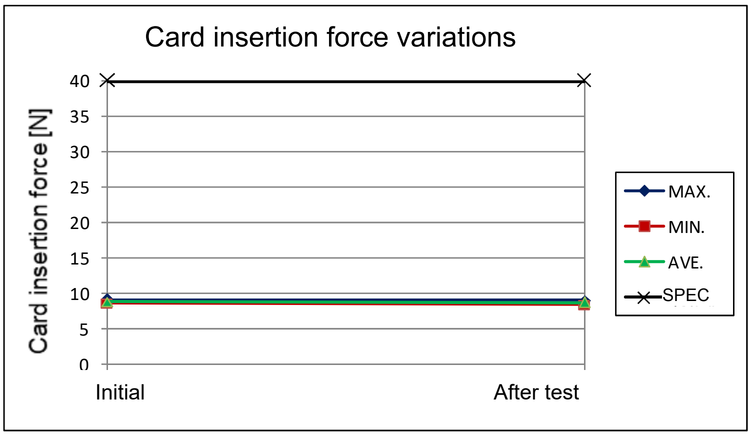


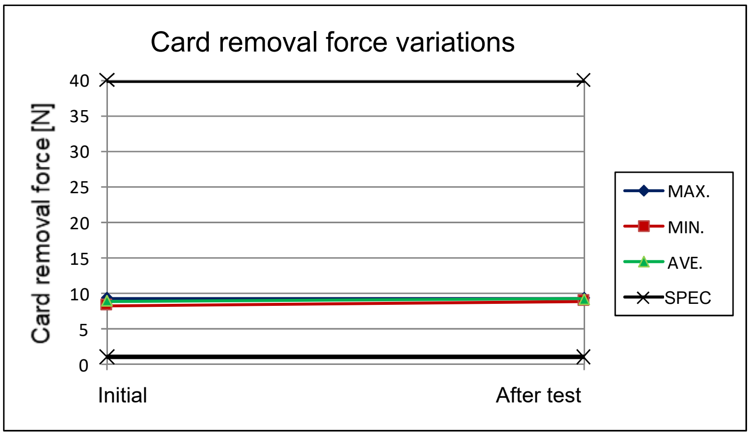






·Card insertion and removal force variations





- Card insertion force : The load for cum-lock
- Card removal force : The load for cum-unlock

- Apperance : There was no deforming, camber and crack of molded parts

Judgment No problems are observed.